

**AMENDMENTS TO THE CLAIMS**

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claims 1-18 (cancelled)

Claim 19. (original) A process for making a bilayered polymeric structure for packaging of electronic components which comprises:

forming a first polymeric sheet from a first molten composition comprising a polymer comprising from 0.26% to 25% by weight of carbon fibrils;

forming a second polymeric sheet from a second molten composition comprising a polymer comprising from 2% to 35% by weight of carbon fibrils; and

combining said first and second sheet into said bilayered polymeric structure.

Claim 20. (original) The process according to claim 19, wherein said layers are combined by lamination or coextrusion, or two shot or multi-shot injection molding or by insert injection molding.

Claim 21. (original) The process according to claim 19, wherein said first and second molten compositions are allowed to become cured after step (c) or cured sequentially.

Claim 22. (original) The process according to claim 19, further comprising adding a conductive adhesive between said first polymeric sheet and said second polymeric sheet.

Claims 23-28 (cancelled).